

SOT931-1

plastic thermal enhanced low profile small outline package;
no leads; 10 terminals; resin based; body 4 x 4 x 1.1 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | D (double) |
| Package type descriptive code | HLSON10R |
| Package type industry code | HLSON10R |
| Package style descriptive code | HLSON (thermal enhanced low profile small outline; no leads) |
| Package style suffix code | R (resin based) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 14-11-2007 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-----|-------|------|
| D | package length | 3.9 | - | 4 | 4.1 | mm |
| E | package width | 3.9 | - | 4 | 4.1 | mm |
| A | seated height | [tbd] | - | 1.1 | 1.3 | mm |
| A ₂ | package height | [tbd] | - | 1.1 | [tbd] | mm |
| n ₂ | actual quantity of termination | - | - | 10 | - | |

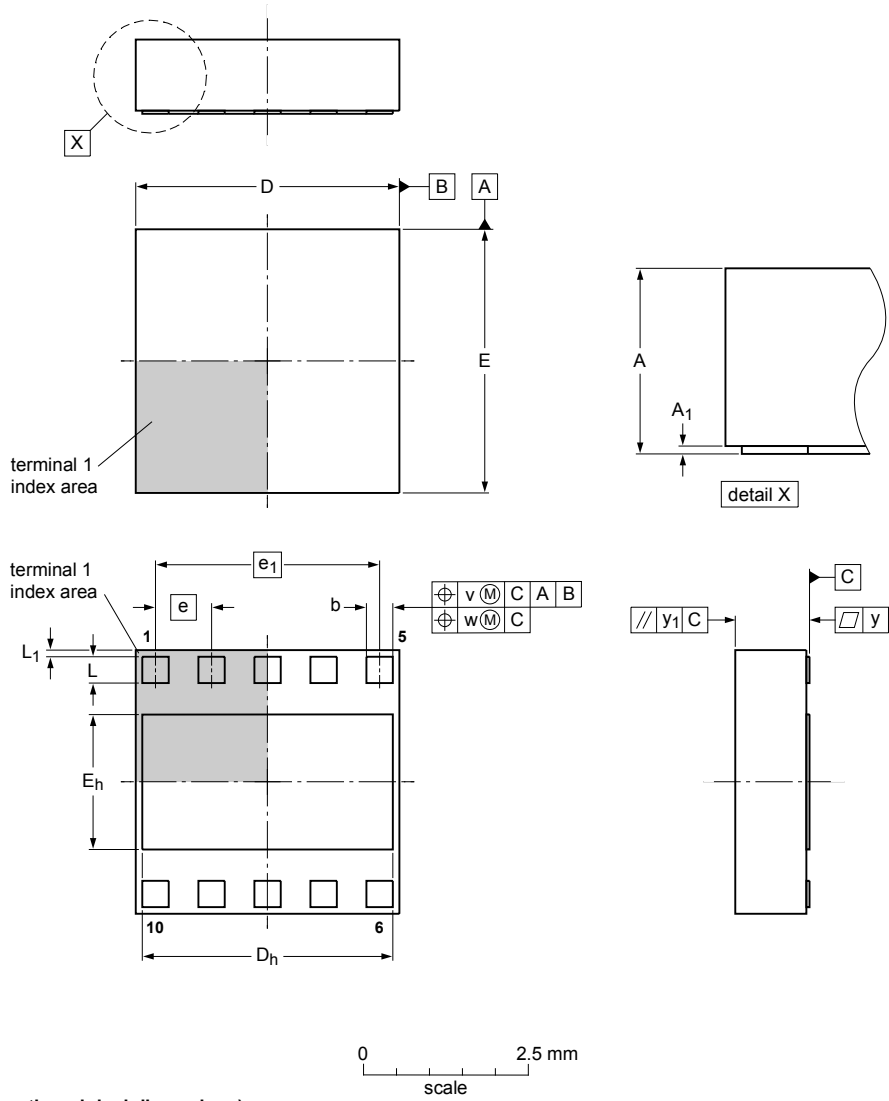


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2. Package outline

HLSON10R: plastic thermal enhanced low profile small outline package; no leads; 10 terminals; resin based; body 4 x 4 x 1.1 mm

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DIMENSIONS (mm are the original dimensions)

| UNIT | A _{max} | A ₁ | b | D | D _h | E | E _h | e | e ₁ | L | L ₁ | v | w | y | y ₁ |
|------|------------------|----------------|--------------|------------|----------------|------------|----------------|------|----------------|--------------|----------------|-----|------|------|----------------|
| mm | 1.3 | 0.05 0.00 | 0.42 0.38 | 4.1 3.9 | 4.0 3.6 | 4.1 3.9 | 2.2 1.8 | 0.85 | 3.4 | 0.42 0.38 | 0.10 0.06 | 0.1 | 0.05 | 0.05 | 0.1 |

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|-------|--|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT931-1 | | | | | | 06-10-10 07-11-14 |

Fig. 1. Package outline HLSON10R (SOT931-1)

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3. Legal information

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